



PRODUCT DATA SHEET



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Datasheet



Resources

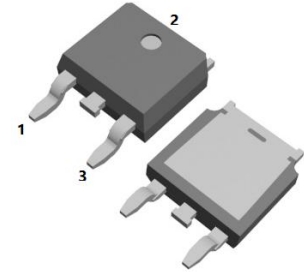


Samples

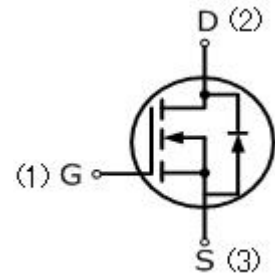
Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

FEATURE

- 7A, 650V, $R_{DS(ON)MAX}=1.4\ \Omega$ @ $V_{GS}=10V/3.5A$
- Low gate charge
- Low C_{iss}
- Fast switching
- 100% avalanche tested
- Improved dv/dt capability



TO-252



Absolute Maximum Ratings($T_C=25^{\circ}C$, unless otherwise noted)			
Parameter	Symbol	JG7N65	UNIT
Drain-Source Voltage	V_{DSS}	650	V
Gate-Source Voltage	V_{GS}	± 30	
Continuous Drain Current	I_D	7	A
Pulsed Drain Current(Note 1)	I_{DM}	28	
Single Pulse Avalanche Energy (Note 2)	E_{AS}	340	mJ
Reverse Diode dV/dt (Note 3)	dv/dt	5	V/ns
Operating Junction and Storage Temperature Range	T_J, T_{STG}	-55to+150	$^{\circ}C$
Maximum lead temperature for soldering purposes, 1/8" from case for 5 seconds	T_L	260	$^{\circ}C$

Parameter	Symbol	JG7N65	Units
Thermal resistance , Channel to Case	$R_{th(ch-c)}$	1.25	$^{\circ}C/W$
Maximum Power Dissipation	P_D	100	W

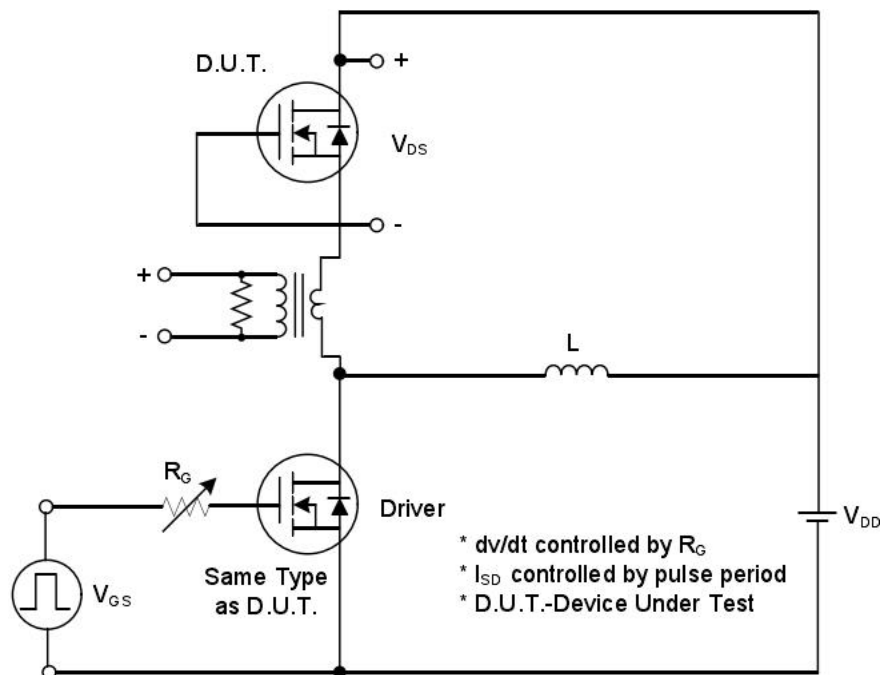
Electrical Characteristics ($T_c=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _D =250uA	650	—	—	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =650V,V _{GS} =0V	—	—	1	uA
Gate-Body Leakage Current,Forward	I _{GSSF}	V _{GS} =30V,V _{DS} =0V	—	—	100	nA
Gate-Body Leakage Current,Reverse	I _{GSSR}	V _{GS} =-30V,V _{DS} =0V	—	—	-100	nA
On Characteristics						
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250uA	2.0	—	4.0	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} =10V,I _D =3.5A	—	1.1	1.4	Ω
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =25V,V _{GS} =0V, f=1.0MHZ	—	1205	—	pF
Output Capacitance	C _{oss}		—	80	—	pF
Reverse Transfer Capacitance	C _{rss}		—	23	—	pF
Switching Characteristics						
Turn-On Delay Time	t _{d(on)}	V _{DD} =325V,I _D =7A, R _G =10Ω	—	15.6	—	ns
Turn-On Rise Time	t _r		—	1.6	—	ns
Turn-Off Delay Time	t _{d(off)}		—	35.6	—	ns
Turn-Off Fall Time	t _f		—	23.6	—	ns
Total Gate Charge	Q _g	V _{DS} =520V,I _D =7A, V _{GS} =10V	—	22.1	—	nC
Gate-Source Charge	Q _{gs}		—	5.8	—	nC
Gate-Drain Charge	Q _{gd}		—	5.4	—	nC
Drain-Source Body Diode Characteristics and Maximum Ratings						
Diode Forward Voltage	V _{SD}	I _S =7A,V _{GS} =0V	—	—	1.5	V
Reverse Recovery Time	t _{rr}	V _{DS} =30V,I _S =1A,	—	382	—	ns
Reverse Recovery Charge	Q _{rr}	dI _F /dt=100A/us,(Note3)	—	1980	—	nC

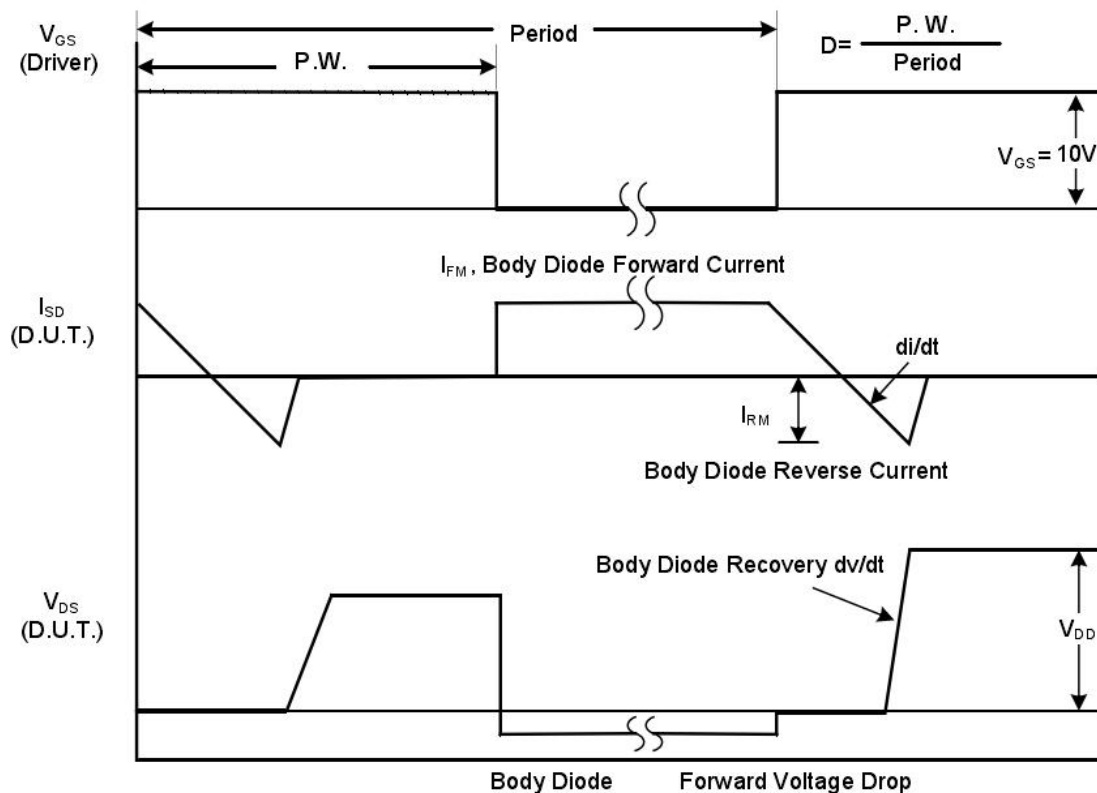
Notes

1. Repetitive Rating; pulse width limited by maximum junction temperature.
2. $V_{DD}=50V, L=10\text{mH}, R_g=25\Omega$, starting $T_J=25^{\circ}\text{C}$.
3. Pulse width $\leq 300\mu s$; duty cycle $\leq 2\%$.

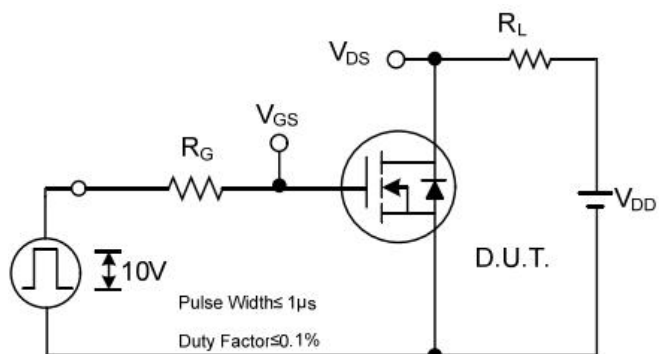
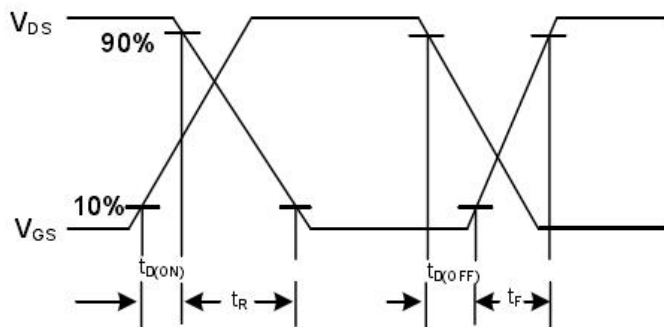
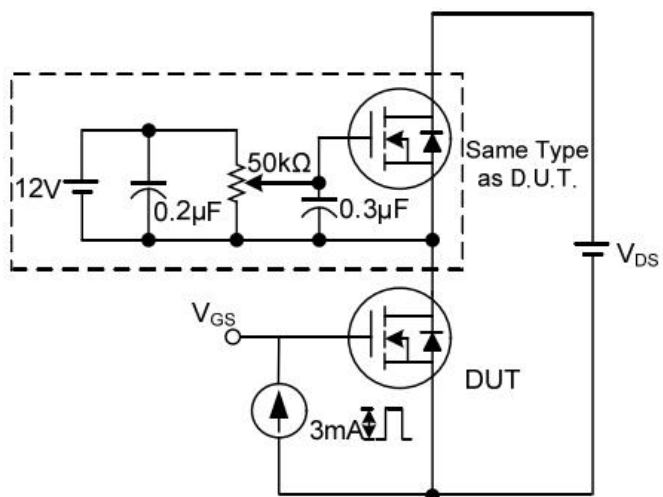
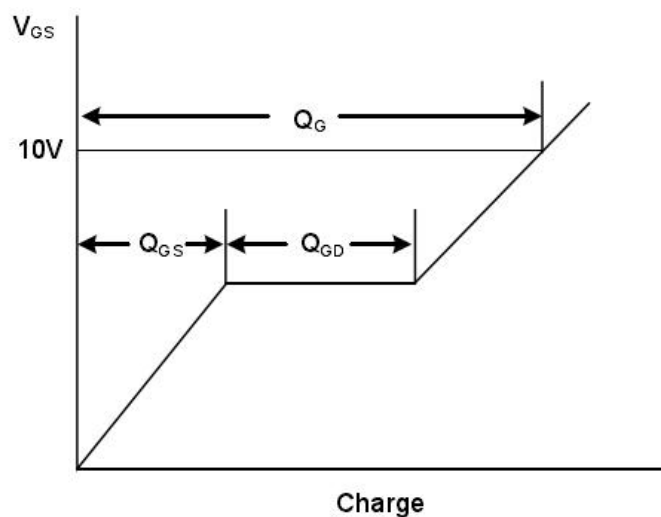
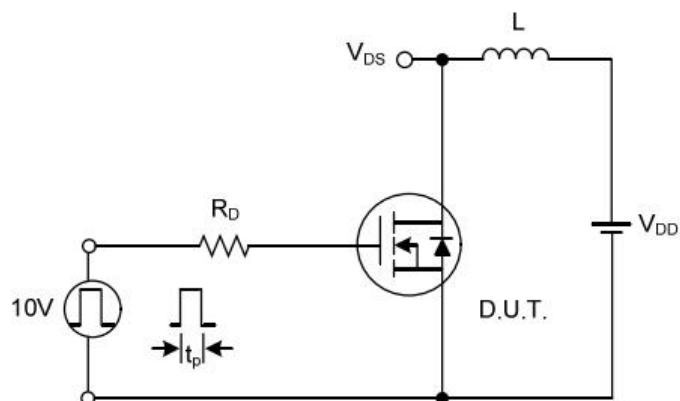
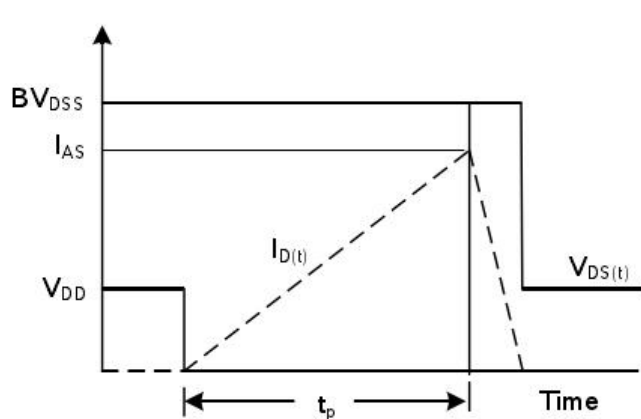
RATING AND CHARACTERISTIC CURVES



Peak Diode Recovery dv/dt Test Circuit



Peak Diode Recovery dv/dt Waveforms


Switching Test Circuit

Switching Waveforms

Gate Charge Test Circuit

Gate Charge Waveform

Unclamped Inductive Switching Test Circuit

Unclamped Inductive Switching Waveforms

RATING AND CHARACTERISTIC CURVES

Figure.1 Typical Output Characteristics

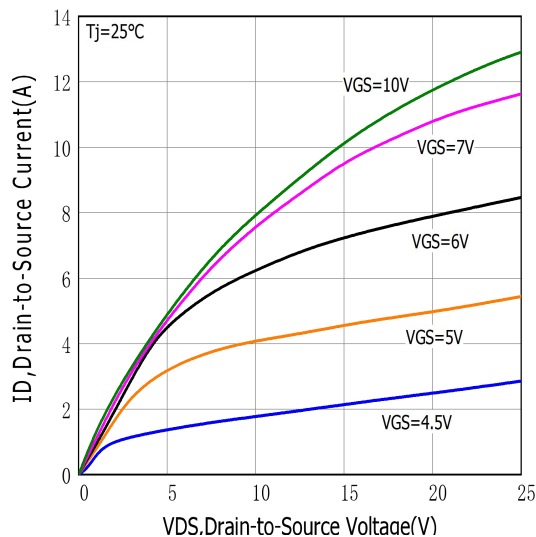


Figure.2 Typical Gate Charge vs Gate to Source Voltage

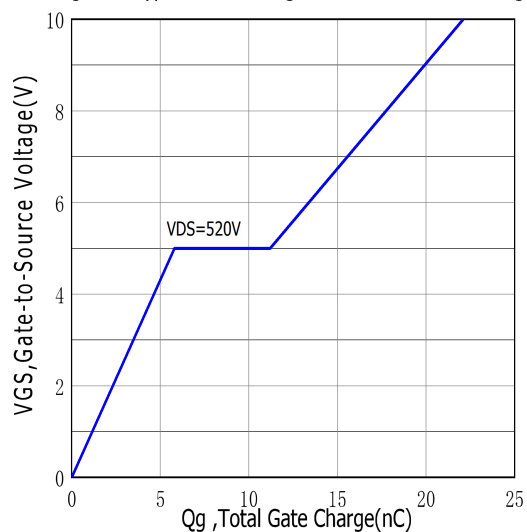


Figure.3 Typical Body Diode Transfer Characteristics

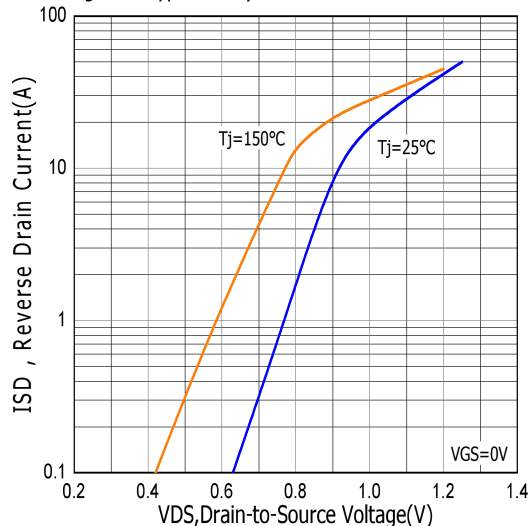


Figure.4 Typical Capacitance vs Drain to Source Voltage

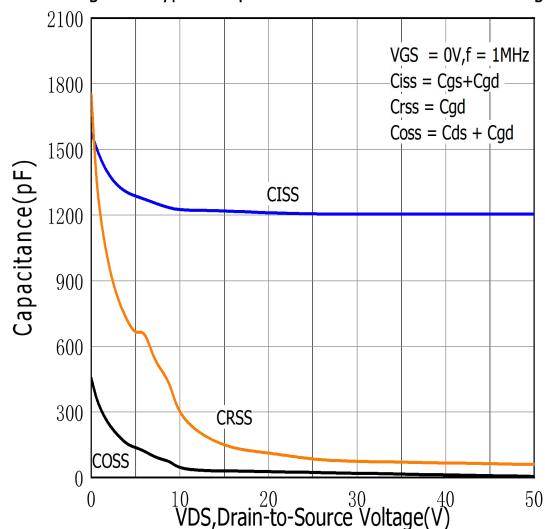


Figure.5 Typical Breakdown Voltage vs Junction Temperature

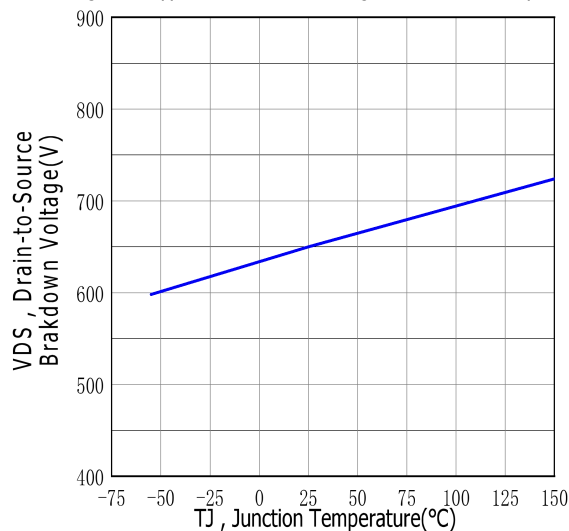


Figure.6 Typical Drain to Source on Resistance vs Junction Temperature

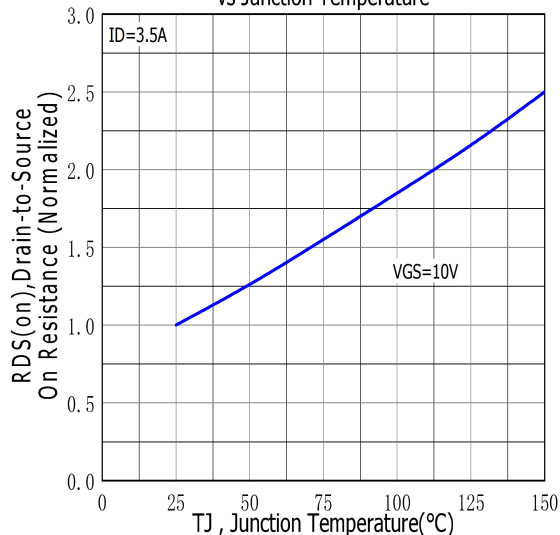


Figure.7 Maximum Forward Bias Safe Operating Area

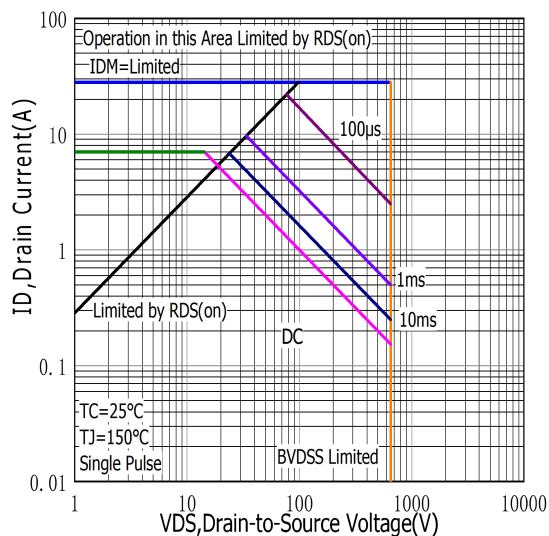


Figure.8 Typical Drain to Source ON Resistance vs Drain Current

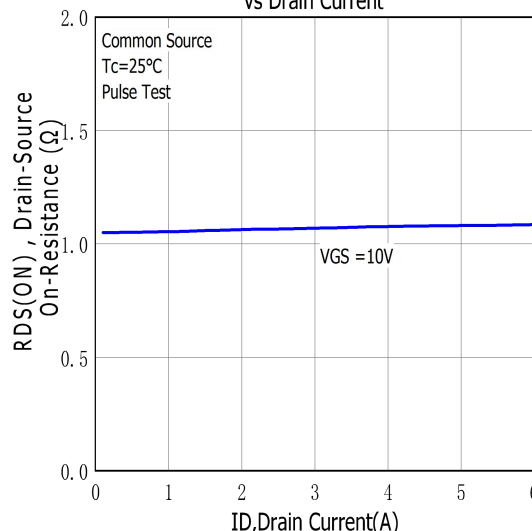


Figure.9 Maximum EAS vs Channel Temperature

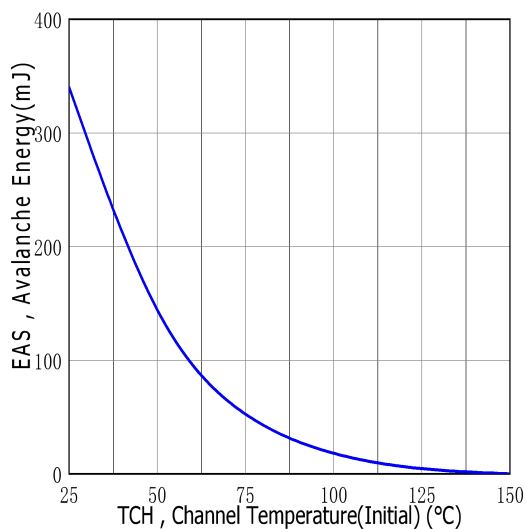


Figure.10 Typical Threshold Voltage vs Case Temperature

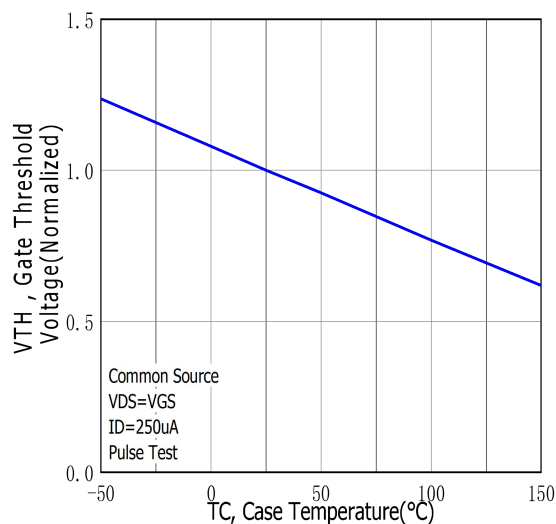


Figure.11 Maximum Effective Thermal Impedance, Junction to Case

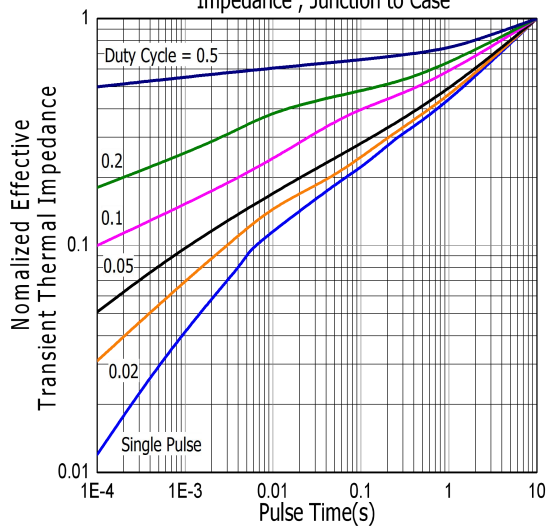
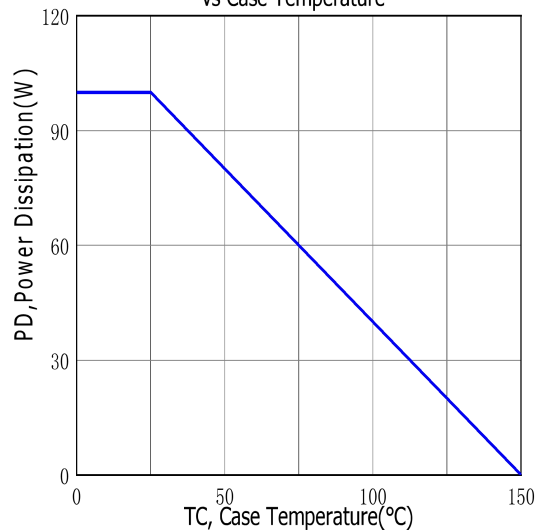
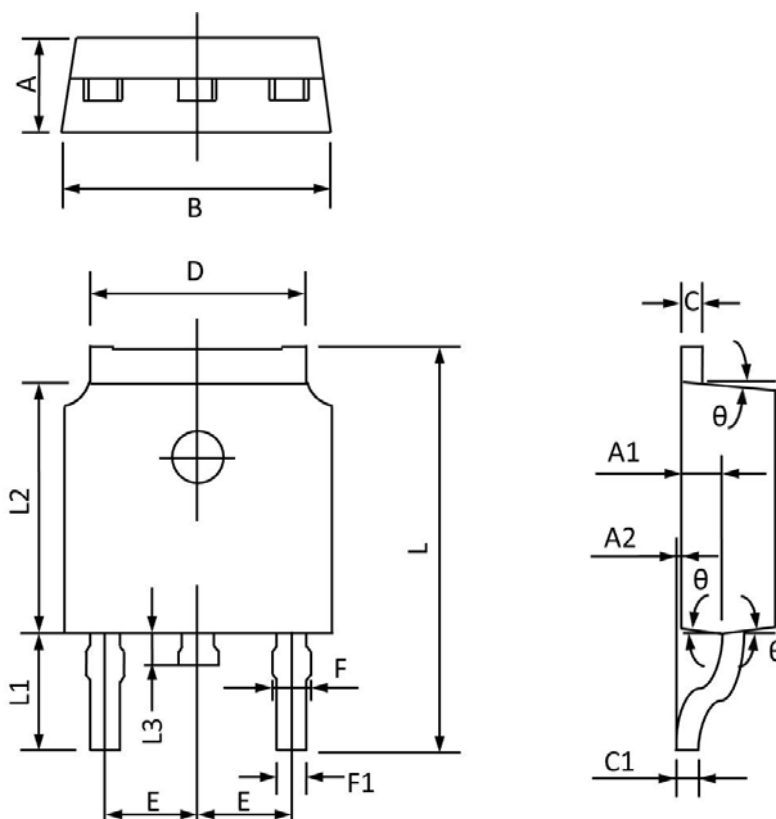


Figure.12 Maximum Power Dissipation vs Case Temperature



TO252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min		Min	Max
A	2.20		0.087	0.094
A1	0.91	1.11	0.03	0.044
A2	0.00		0.000	0.006
B	6.50	6.70	0.256	0.264
C	0.46	0.580	0.018	0.230
C1	0.4	0.580	0.018	0.030
D	5.10	5.46	0.201	0.215
E	2.186	2.386	0.086	0.094
F	0.74	0.94	0.029	0.037
F1	0.66	0.860	0.026	0.034
L	9.80	10.40	0.386	0.409
L1	2.9R		0.114REF	
L2	6.0	6.20	0.236	0.244
L3	0.6	1.00	0.024	0.039
θ	3°	9°	3°	9°

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